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Please note: As part of the Fairchild Semiconductor integration, some of the Fairchild orderable part numbers will need to change in order to meet ON Semiconductor's system requirements. Since the ON Semiconductor product management systems do not have the ability to manage part nomenclature that utilizes an underscore (_), the underscore (_) in the Fairchild part numbers will be changed to a dash (-). This document may contain device numbers with an underscore (_). Please check the ON Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.onsemi.com. Please email any questions regarding the system integration to Fairchild guestions@onsemi.com.

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June 2015

FDBL0150N60

N-Channel PowerTrench® MOSFET **60 V, 240 A, 1.5 m**Ω

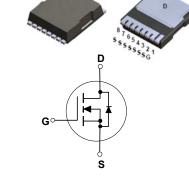
Features

- Typical $R_{DS(on)}$ = 1.1 $m\Omega$ at V_{GS} = 10V, I_D = 80 A
- Typical $Q_{q(tot)}$ = 130 nC at V_{GS} = 10V, I_D = 80 A
- UIS Capability
- RoHS Compliant

Applications

- Industrial Motor Drive
- Industrial Power Supply
- Industrial Automation
- Battery Operated tools
- Battery Protection
- Solar Inverters
- UPS and Energy Inverters
- Energy Storage
- Load Switch





For current package drawing, please refer to the Fairchild website at http://www.fairchildsemi.com/dwg/PS/PSOF08A.pdf.

MOSFET Maximum Ratings T_J = 25°C unless otherwise noted.

Symbol	Parameter	Ratings	Units	
V_{DSS}	Drain-to-Source Voltage		60	V
V_{GS}	Gate-to-Source Voltage		±20	V
	Drain Current - Continuous (V _{GS} =10) (Note 1)	T _C = 25°C	240	Α
ID	Pulsed Drain Current	T _C = 25°C	See Figure 4	7 ^
E _{AS}	Single Pulse Avalanche Energy	(Note 2)	614	mJ
D	Power Dissipation		357	W
P_{D}	Derate Above 25°C		2.38	W/°C
T _J , T _{STG}	Operating and Storage Temperature		-55 to + 175	°C
$R_{\theta JC}$	Thermal Resistance, Junction to Case		0.42	°C/W
$R_{\theta JA}$	Maximum Thermal Resistance, Junction to Ambient	(Note 3)	43	°C/W

Notes:

- Current is limited by silicon.
 Starting T_J = 25°C, L = 0.3mH, I_{AS} = 64A, V_{DD} = 60V during inductor charging and V_{DD} = 0V during time in avalanche.
 R_{0JA} is the sum of the junction-to-case and case-to-ambient thermal resistance, where the case thermal reference is defined as the solder resulting surface of the drain pine. P_D is guaranteed by design, while P_D is determined by the hoard design. The maximum rating mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design, while $R_{\theta JA}$ is determined by the board design. The maximum rating presented here is based on mounting on a 1 in² pad of 2oz copper.

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDBL0150N60	FDBL0150N60	MO-299A	13"	24mm	2000 units

Units

Max.

Electrical Characteristics $T_J = 25^{\circ}C$ unless otherwise noted.

Parameter

Off Characteristics								
B _{VDSS}	Drain-to-Source Breakdown Voltage	$I_D = 250 \mu A$,	V _{GS} = 0V	60	-	-	V	
ı	Drain-to-Source Leakage Current	V _{DS} =60V,	$T_J = 25^{\circ}C$	-	-	1	μА	
IDSS		$V_{GS} = 0V$	$T_J = 175^{\circ}C \text{ (Note 4)}$	-	-	1	mA	
I _{GSS}	Gate-to-Source Leakage Current	$V_{GS} = \pm 20V$		-	-	±100	nA	

Test Conditions

Min.

Тур.

On Characteristics

Symbol

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$		2.0	2.9	4.0	V
R _{DS(on)}	Drain to Source On Resistance	I _D = 80A,	$T_{J} = 25^{\circ}C$	-	1.1	1.5	mΩ
		V _{GS} = 10V	$T_J = 175^{\circ}C \text{ (Note 4)}$	-	2.1	2.9	mΩ

Dynamic Characteristics

C _{iss}	Input Capacitance	.,	V _{DS} = 30V, V _{GS} = 0V, f = 1MHz		10300	-	pF
C _{oss}	Output Capacitance				2590	-	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1101112			270	-	pF
R_g	Gate Resistance	f = 1MHz	f = 1MHz		4.3	-	Ω
$Q_{g(ToT)}$	Total Gate Charge at 10V	V _{GS} = 0 to 10V	V _{DD} = 48V	-	130	169	nC
Q _{g(th)}	Threshold Gate Charge	$V_{GS} = 0$ to 2V	$V_{GS} = 0 \text{ to } 2V$ $I_D = 80A$		19	-	nC
Q_{gs}	Gate-to-Source Gate Charge		_	-	48	-	nC
Q_{qd}	Gate-to-Drain "Miller" Charge			-	20	-	nC

Switching Characteristics

t _{on}	Turn-On Time	V_{DD} = 30V, I_{D} = 80A, V_{GS} = 10V, R_{GEN} = 6Ω	-	-	160	ns
t _{d(on)}	Turn-On Delay		-	30	-	ns
t _r	Rise Time		-	77	-	ns
t _{d(off)}	Turn-Off Delay		-	78	-	ns
t _f	Fall Time		-	57	-	ns
t _{off}	Turn-Off Time		-	ı	200	ns

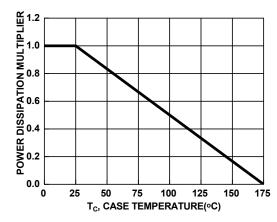
Drain-Source Diode Characteristics

V _{SD}	Source-to-Drain Diode Voltage	I _{SD} =80A, V _{GS} = 0V	-	-	1.25	V
		I _{SD} = 40A, V _{GS} = 0V	-	-	1.2	V
t _{rr}	Reverse-Recovery Time	$I_F = 80A$, $dI_{SD}/dt = 100A/\mu s$,	-	94	140	ns
Q _{rr}	Reverse-Recovery Charge	V _{DD} =48V	-	131	200	nC

Note:

4: The maximum value is specified by design at T_J = 175°C. Product is not tested to this condition in production.

Typical Characteristics



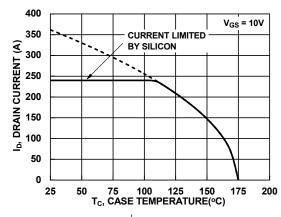


Figure 1. Normalized Power Dissipation vs. Case Temperature

Figure 2. Maximum Continuous Drain Current vs.

Case Temperature

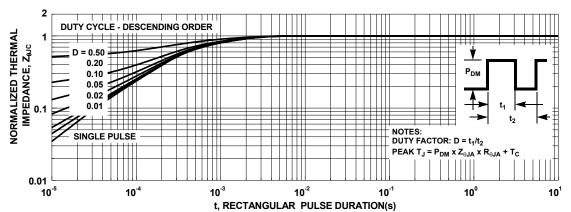


Figure 3. Normalized Maximum Transient Thermal Impedance

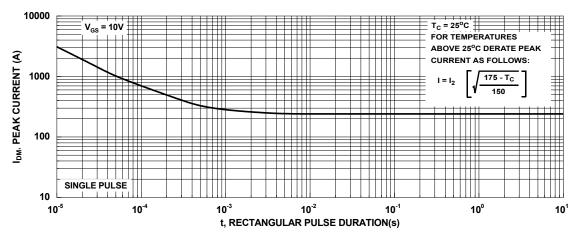


Figure 4. Peak Current Capability

Typical Characteristics

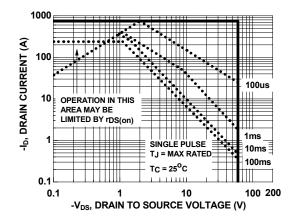
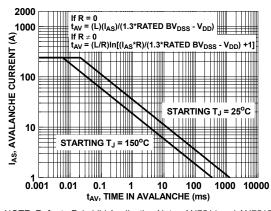


Figure 5. Forward Bias Safe Operating Area



NOTE: Refer to Fairchild Application Notes AN7514 and AN7515

Figure 6. Unclamped Inductive Switching

Capability

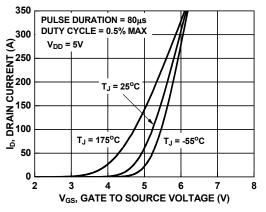


Figure 7. Transfer Characteristics

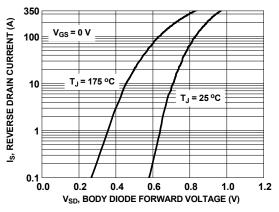


Figure 8. Forward Diode Characteristics

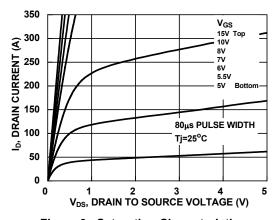


Figure 9. Saturation Characteristics

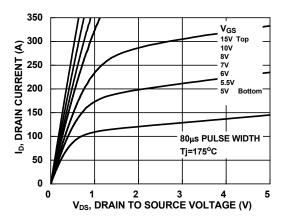


Figure 10. Saturation Characteristics

Typical Characteristics

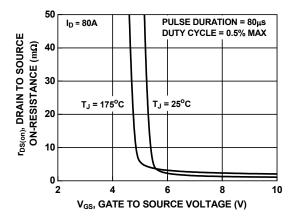


Figure 11. R_{DSON} vs. Gate Voltage

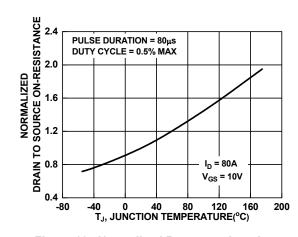


Figure 12. Normalized R_{DSON} vs. Junction Temperature

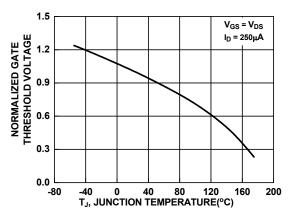


Figure 13. Normalized Gate Threshold Voltage vs. Temperature

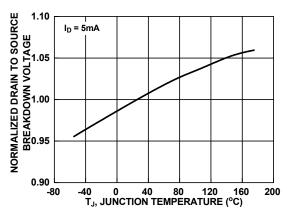


Figure 14. Normalized Drain to Source Breakdown Voltage vs. Junction Temperature

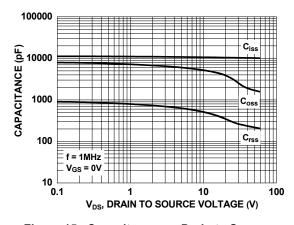


Figure 15. Capacitance vs. Drain to Source Voltage

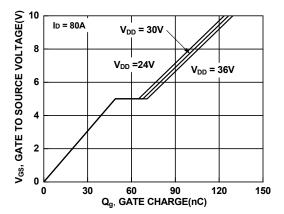
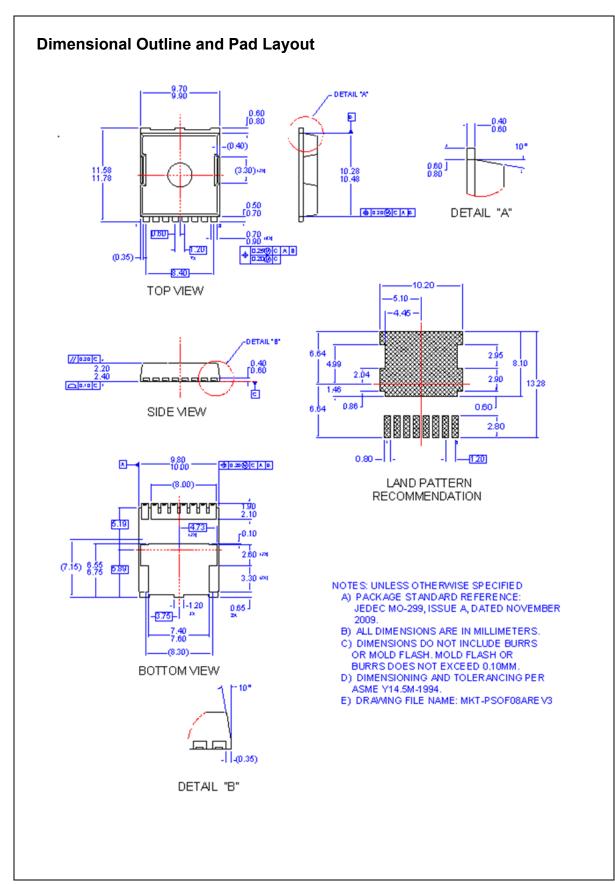
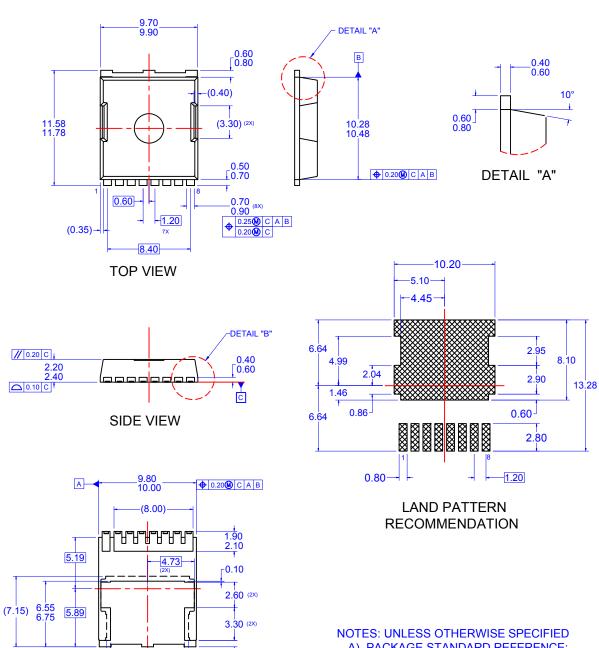


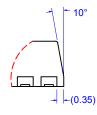
Figure 16. Gate Charge vs. Gate to Source Voltage





- A) PACKAGE STANDARD REFERENCE: JEDEC MO-299, ISSUE A, DATED NOVEMBER 2009.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.
- D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- E) DRAWING FILE NAME: MKT-PSOF08AREV3

3.3 3.3 3.3 3.75 3.75 3.75 3.75 2.7.40 7.60 (8.30) BOTTOM VIEW



DETAIL "B"

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